**PACKAGING & ASSEMBLY SERVICES**

- **Sub-contract design and assembly for optoelectronics and microelectronic devices**
  - Small batch prototypes through to volume manufacturing

- **Design Services**
  - Optical, mechanical & thermal modelling
  - Advanced electro / optical package design
  - Design for manufacture

- **MIL-STD-883 and ESCC Standards**
  - Focussed areas of excellence
    - Wafer processing
    - Precision placement and auto die attach
    - Wire Bond – Au & Al, ball & wedge
    - Hermetic sealing
    - Optical alignment
    - Laser packaging
    - Photonic IC packaging

- **Experienced end-to-end Manufacturer:**
  - Wafer processing through to finished packaged product
  - ISO7 Clean Room assembly
  - Optoelectronic & Optical Packaging
  - Microelectronic & MEMS Packaging
  - Electrical and optical test

- **QC & Inspection**
  - Die shear and wire strength tests
  - Real-time X-RAY
  - Placement accuracy measurements

- **Working with our parent Alter Technology to provide fully tested & qualified product solutions**
  - EEE procurement, Test, Screening & Qualification

[www.altertechnology-group.com](http://www.altertechnology-group.com)